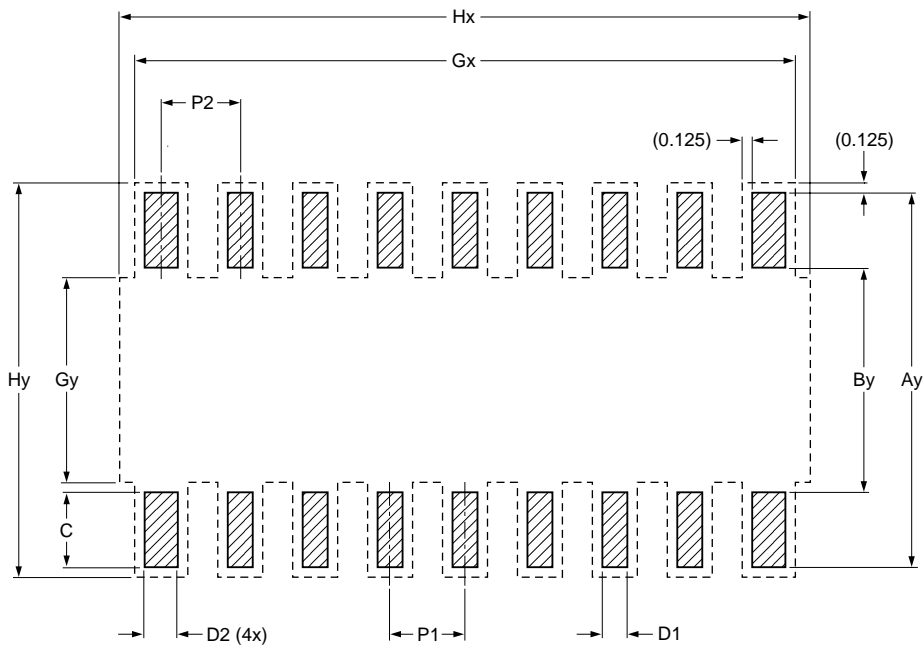



Footprint information for reflow soldering of TSSOP8 package

SOT505-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
 - - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.725	5.500	3.200	1.150	0.450	0.600	2.950	3.600	3.600	5.750